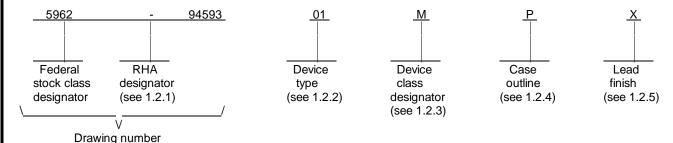
THIS RE	Form Approved OMB No. 0704-0188						
Public reporting but existing data source regarding this Department of De	urden for thi ces, gatherii burden es efense, Washi	is collection is estimate ng and maintaining the timate or any other a ingtion Headquarters S	ed to average 2 ho data needed, and spect of this colle ervices, Directorat	ours per response, included completing and review ection of information, include for Information Operat	ding the time for reviewing ing the collection of inforn cluding suggestions for ro- ions and Reports, 1215 Ju	instructions, searching nation. Send comments educing this burden, to efferson Davis Highway.	2. PROCURING ACTIVITY NO.
Public reporting burden for this collection is estimated to average 2 hours per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Department of Defense, Washingtion Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188), Washington, DC 20503. PLEASE DO NOT RETURN YOUR COMPLETED FORM TO EITHER OF THESE ADDRESSED. RETURN COMPLETED FORM TO THE GOVERNMENT ISSUING CONTRACTING OFFICER FOR THE CONTRACT/ PROCURING ACTIVITY NUMBER LISTED IN ITEM 2 OF THIS FORM.							3. DODAAC
4. ORIGINATO			b. ADDRESS (S	Street, City, State, Zip Coronics Supply Center		5. CAGE CODE 67268	6. NOR NO. 5962-R179-96
a. TYPED NAN	ΛΕ (First, M	1iddle Initial,	1507 Wilmington, OH 45			7. CAGE CODE 67268	8. DOCUMENT NO. 5962-94593
9. TITLE OF D		R, 800 MHz, CURREI	NT FEEDBACK A	MPLIFIER,	10. REVISION LETTER	\	11. ECP NO.
MONOLITHIC	C SILICON				a. CURRENT	b. NEW	No users listed.
12. CONFIGUE	RATION ITE	EM (OR SYSTEM) TO	WHICH ECP AP	PLIES			
13. DESCRIPT	TION OF RI	EVISION					
Rev Rev Rev Sheet 5: TAI Cor Pov de	visions desovisions date visions level li vision level li vistatus of selections mod ver supply relete the mi	e column; add "96-07- block; add "D". sheets; for sheets 1 ar e rejection ratio test.	nd 5, add "A". For subgroups 2 aith the conditions	of -VS = -4 V to -6 V and	R179-96". limit of "50 dB" and subst d +VS = +5 V, for subgro		
14. THIS SECT	TION FOR	GOVERNMENT USE	ONLY				
a. (X one)	Х	(1) Existing documer	nt supplemented t	by the NOR may be use	ed in manufacture.		
		(2) Revised docume	nt must be receive	ed before manufacturer	may incorporate this cha	ange.	
		(3) Custodian of mas	ster document sha	all make above revision	and furnish revised docu	ment.	
b. ACTIVITY AL	JTHORIZEI	D TO APPROVE CHA	NGE FOR GOVE	ERNMENT	c. TYPED NAME (First,	Middle Initial, Last)	
DESC-ELDS	3				MICHAEL FRYE		
d. TITLE				e. SIGNATURE			f. DATE SIGNED (YYMMDD)
CHIEF, MICF	ROELECTR	RONICS BRANCH		MICHAEL FRYE			96-07-11
15a. ACTIVITY	ACCOMPL	LISHING REVISION		b. REVISION COMPLI	ETED (Signature)		c. DATE SIGNED (YYMMDD)
DESC-ELDS RICK OFFICER					96-07-11		

								F	REVISI	IONS										
LTR	. 	DESCRIPTION										D:	ATE (Y	/R-MO-D	DA)		APPF	ROVED)	
REV						<u> </u>	<u> </u>	<u> </u>				<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	
SHEET							<u> </u> !	<u> </u>	ļ!			<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u> !	<u> </u>	<u> </u>
REV							<u> </u> !	<u> </u>	ļ!			<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u> !	\bigsqcup	<u> </u>
SHEET							<u> </u> !	<u> </u>	<u> </u>			<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u> !	<u> </u>	<u> </u>
REV STATUS OF SHEETS	3			RE\			<u> </u> !	<u> </u>	<u> </u>			<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	\bigsqcup	<u> </u>
				SHE	ET		1	2	3	4	5	6	7	8	9		<u> </u>			
PMIC N/A				PARED CK OFF	D BY FICER					DE	EFENS			ONICS N, OHIO			ENTE	R		
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE		Γ		CKED AJESH	BY I PITHA	ADIA														
		М		L FRYE												RENT LICON				
					96-0	OVAL D 04-29	ATE		SIZE	4		E COD			59)62-	-945	593		
AMSC 1	√A			KEVI	SIUN	LEVEL								<u> </u>						
									ŀ	SHE	ΕI	1	(OF	9					

1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.
 - 1.2 PIN. The PIN is as shown in the following example:



- 1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	AD8001	800 MHz, current feedback amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

Device class Device requirements documentation

M Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN

class level B microcircuits in accordance with MIL-PRF-38535, appendix A

Q or V Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Р	GDIP1-T8 or CDIP2-T8	8	Dual-in-line

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE A		5962-94593
	REVISION LEVEL	SHEET 2

1.3 Absolute maximum ratings. 1/

Input voltage (common mode) ±V_S Differential input voltage ±1.2 V

Storage temperature range -65° C to +125° C

Lead temperature range (soldering, 30 seconds) +300° C

1.4 Recommended operating conditions.

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

MILITARY

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.

HANDBOOKS

MILITARY

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

STANDARD MICROCIRCUIT DRAWING **DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444**

SIZE A		5962-94593
	REVISION LEVEL	SHEET 3

Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

Maximum internal power dissipation is specified so that the junction temperature dose not exceed +175°C. Derate at 9 mW/ $^{\circ}$ C for $T_A > +32^{\circ}$ C.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-94593
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 4

TABLE I. <u>Electrical performance characteristics</u> .									
Test	Symbol	Conditions 1	<u>l</u> /	Group		Device	Liı	mits	Unit
		-55°C ≤ T _A ≤ +1 unless otherwise spe	25°C ecified	subgro	oups	Туре	Min	Max	
DC performance section									
Input offset voltage	Vos			1		01		5.5	mV
				2,3				9.0	
Positive input bias current	+I _{IB}			1		01	-6	+6	μΑ
- Carrott				2,3			-12	+12	
Negative input bias current	-I _{IB}			1		01	-25	+25	μΑ
				2,3			-35	+35	<u> </u>
Open loop transresistance	R _{OLT}	$V_{OUT} = \pm 2.5 \text{ V}$		4		01	250		kΩ
				5,6			175		<u> </u>
Input characteristics section									
Common mode rejection ratio	CMRR	$V_{CM} = \pm 2.5 \text{ V}$		1,2,	3	01	50		dB
Output characteristics section									
Output voltage swing	V _{OUT}	R _L = 150 Ω		1		01	-2.7	+2.7	V
				2,3			-2.6	+2.6	
Output current	I _{OUT}	$R_L = 37.5 \Omega, T_A = +2$	25° C	1		01	50		mA
Short circuit current	los	T _A = +25°C		1		01	85		mA
Power supply section					•	•			
Power supply operating range	V _{PS}			1,2,	3	01	±3	±6	V
Quiescent current	lQ			1		01		5.5	mA
				2,3				6.0	
Power supply rejection ratio	PSRR	$+V_S = +4 \text{ V to } +6 \text{ V},$ $-V_S = -5 \text{ V}$		1,2,	3	01	60		dB
		$-V_S = -4 \text{ V to } -6 \text{ V},$ + $V_S = +5 \text{ V}$					50		
See footnotes at end of table.									
STAN MICROCIRCU		NG	SIZ A					596	62-94593
DEFENSE ELECTRON DAYTON, C	ICS SUPP	LY CENTER			REV	ISION LE\	/EL	SHEE	T 5

TABLE I. <u>Electrical performance characteristics</u> - Continued.								
Test	Symbol	Conditions 1/	Group A	Device Type	Limits		Unit	
		-55°C ≤ T _A ≤ +125°C unless otherwise specified	-55°C ≤ T _A ≤ +125°C subgroups unless otherwise specified		Min	Max		
Dynamic performance section								
Small signal bandwidth 2/	SSBW	-3 dB, G = +2, R _F = 750 Ω, peaking < 0.1 dB, T_A = +25°C	4	01	350		MHz	
		-3 dB, G = +1, R_F = 1 k Ω , peaking < 1 dB, T_A = +25°C			650			
Bandwidth for 0.1 dB <u>2</u> / flatness	BW	$G = +2$, $R_F = 750 Ω$, $T_A = +25$ °C	4	01	85		MHz	
Slew rate 2/	SR	$G = +2, V_{OUT} = 2 \text{ V step},$ $T_A = +25^{\circ}C$	4	01	800		V/µs	
		$G = -1$, $V_{OUT} = 2$ V step, $T_A = +25$ °C			960			
Noise and harmonic performance section								
Differential gain error 2/	DGE	$G = +2, R_L = 150 \Omega,$ $T_A = +25^{\circ}C$	4	01		0.025	%	
Differential phase 2/ error	DPE	$G = +2$, $R_L = 150 Ω$, $T_A = +25°C$	4	01		0.04	Degree	

 $[\]underline{1}$ / Unless otherwise specified, $V_S = \pm 5$ V and $R_L = 100 \ \Omega$.

4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^{\circ} C$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-94593
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 6

^{2/} If not tested, shall be guaranteed to the limits specified in table I herein.

Device type	01
Case outline	Р
Terminal number	Terminal symbol
1	NC
2	-INPUT
3	+INPUT
4	-V _S
5	NC
6	OUTPUT
7	+V _S
8	NC

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-94593
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 7

- 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
 - 4.4.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.
 - 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - b. $T_A = +125^{\circ} C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - 4.4.3 <u>Group D inspection</u>. The group D inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5°C, after exposure, to the subgroups specified in table II herein.
 - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-94593
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 8

TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgr (in accorda MIL-PRF-38	ance with
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)			
Final electrical parameters (see 4.2)	1,2,3, <u>1</u> / 4,5,6	1,2,3, <u>1</u> / 4,5,6	1,2,3, <u>1</u> / 4,5,6
Group A test requirements (see 4.4)	1,2,3, 4,5,6	1,2,3, 4,5,6	1,2,3, 4,5,6
Group C end-point electrical parameters (see 4.4)	1	1	1,2,3, 4,5,6
Group D end-point electrical parameters (see 4.4)	1	1	1,2,3, 4,5,6
Group E end-point electrical parameters (see 4.4)			

^{1/} PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 Record of users. Military and industrial users should inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-94593
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 9

6.6 Sources of supply.			
6.6.1 <u>Sources of supply for device classes Q and V</u> . Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.			
6.6.2 <u>Approved sources of supply for device class M</u> . Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.			
STANDARD	SIZE		5962-94593
MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	Α	REVISION LEVEL	SHEET
DAYTON, OHIO 45444		VIOIOIVELVEL	10

STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 96-04-29

Approved sources of supply for SMD 5962-94593 are listed below for immediate acquisition only and shall be added to MIL-HDBK-103 during the next revision. MIL-HDBK-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-HDBK-103.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9459301MPA	24355	AD8001SQ

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. The device manufacturers listed herein are authorized to supply alternate lead finishes "A", "B", or "C" at their discretion. Contact the listed approved source of supply for further information.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

 Vendor CAGE
 Vendor name

 number
 and address

24355 Analog Devices, Incorporated

Route 1 Industrial Park Norwood, MA 02062-9106

Point of contact: 804 Woburn Street

Wilmington, MA 01887-3462

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.